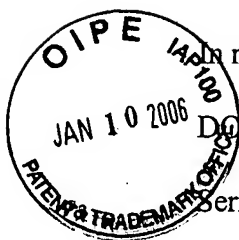


DFW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



In re the Application of

DONALD C. ABBOTT ET AL.

Serial No. 10/724,498 (TI-28098.1)

Filed: December 1, 2003

For: SEMICONDUCTOR CIRCUIT ASSEMBLY HAVING PLATED LEADFRAME  
INCLUDING GOLD SELECTIVELY COVERING AREAS TO BE SOLDERED

Art Unit 2814

Examiner Wael M. Fahmy

Customer No. 23494

Director of the United States  
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*[Signature]*

Jay M. Cantor, Reg. No. 19,906

**AMENDMENT UNDER 37 C.F.R. 1.111**

Dear Sir:

In response to the Office action dated October 14, 2005, please amend the above-identified application as follows: